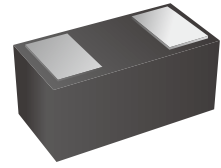


Low Capacitance TVS/ESD Protection Diode

Features

- IEC61000-4-2 (ESD) $\pm 20\text{kV}$ (Contact)
- IEC61000-4-2 (ESD) $\pm 30\text{kV}$ (Air)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lighting) 3A (8/20 μs)
- 150 Watts Peak Pulse Power ($t_p=8/20\mu\text{s}$)
- Working voltages : 24V
- Low clamping voltage
- Low leakage current
- Lead free in comply with EU RoHS 011/65/EU directives



Mechanical Data

- Case:DFN1006
- Flammability Rating: UL 94V-0
- Material: Halogen free

Applications

- Serial and Parallel Ports
- Notebooks, Desktops, Servers
- Projection TV
- Cellular handsets and accessories
- Portable instrumentation
- Peripherals

Ordering Information

Part Number	Marking	Shipping	Reel
LTE10N24C01L-TR10	DH	10000PCS Tape&Reel	7 inches

Absolute Maximum Rating

Symbol	Parameter	Value	Unit
V_{ESD}	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	± 20 ± 30	kV
P_{PP}	Peak Pulse Power (8/20 μs)	150	W
T_{OPT}	Operating Temperature	-55 ~ +125	$^{\circ}\text{C}$
T_{STG}	Storage Temperature	-55 ~ +150	$^{\circ}\text{C}$
T_L	Lead Soldering Temperature	260 (10 sec.)	$^{\circ}\text{C}$



Electrical Characteristics (Tamb=25°C)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
V _{RWM}	Reverse Working Voltage				24	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA	26		32	V
I _R	Reverse Leakage Current	V _{RWM} = 24V			1	μA
V _{C1}	Clamping Voltage 1	I _{PP} = 1A, t _p = 8/20μs			40	V
V _{C2}	Clamping Voltage 2	I _{PP} = 3A, t _p = 8/20μs			50	V
C _J	Junction Capacitance	V _R = 0V, f = 1MHz		8	15	pF

Characteristics Curve

Fig.1 8/20us Waveform per IEC61000-4-5

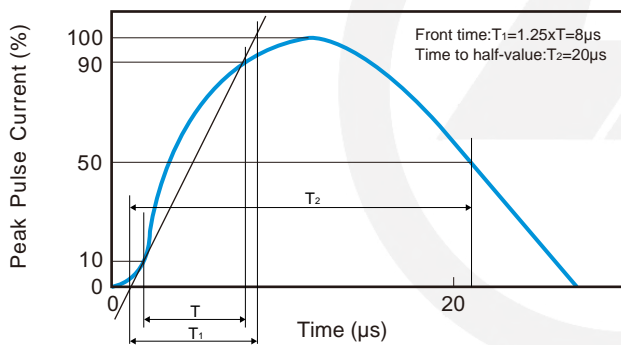


Fig.2 Contact Discharge Current Waveform per IEC 61000-4-2

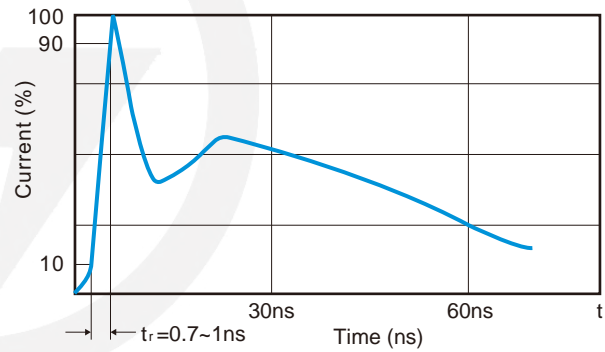


Fig.3 Voltage vs Capacitance

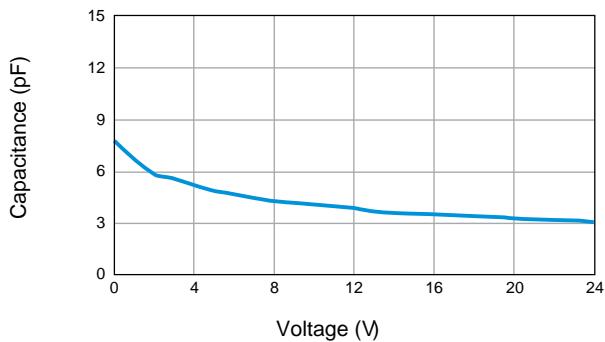
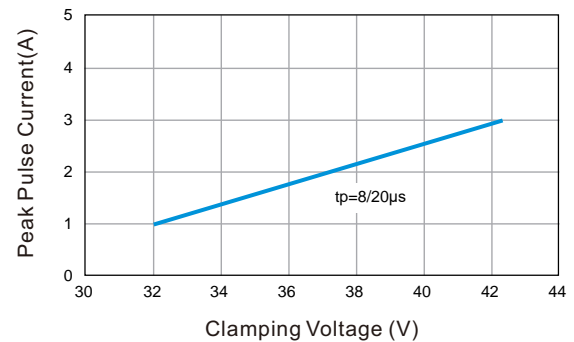
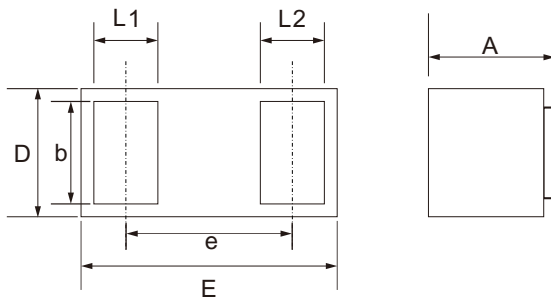


Fig.4 Clamping Voltage vs Peak Pulse Current



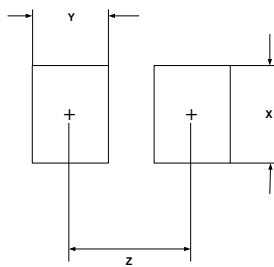
DFN1006 Package Outline

Unit: mm



SYMBOL	DIMENSIONS	
	MIN.	MAX.
D	0.550	0.650
E	0.950	1.050
L1	0.200	0.300
L2	0.200	0.300
b	0.450	0.550
e	0.650 TYP.	
A	0.450	0.550

DFN1006 Suggested Pad Layout



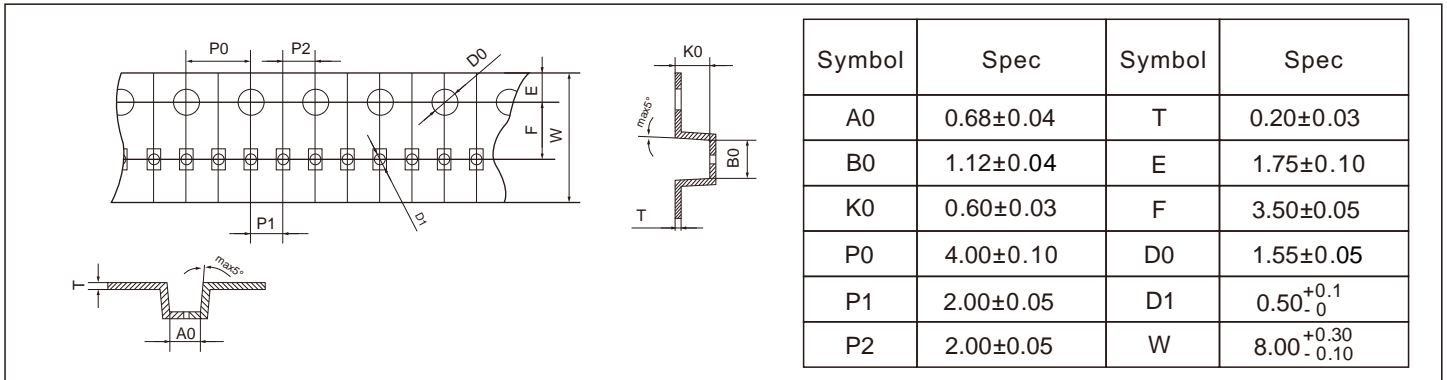
SYM	DIMENSIONS	
	MILLIMETERS	
X	0.50	
Y	0.50	
Z	0.90	

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purpose only.

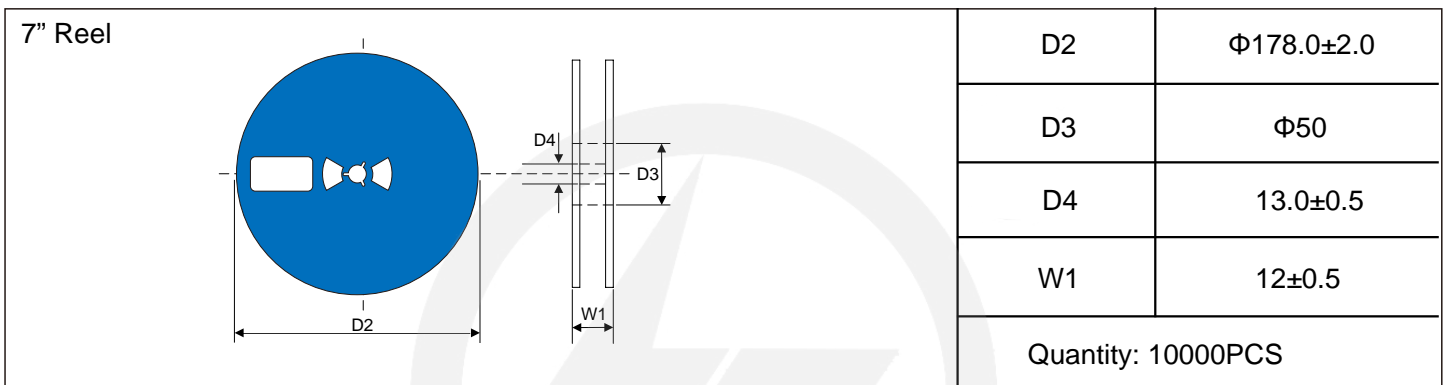
Carrier Tape Dimensions

Unit : mm

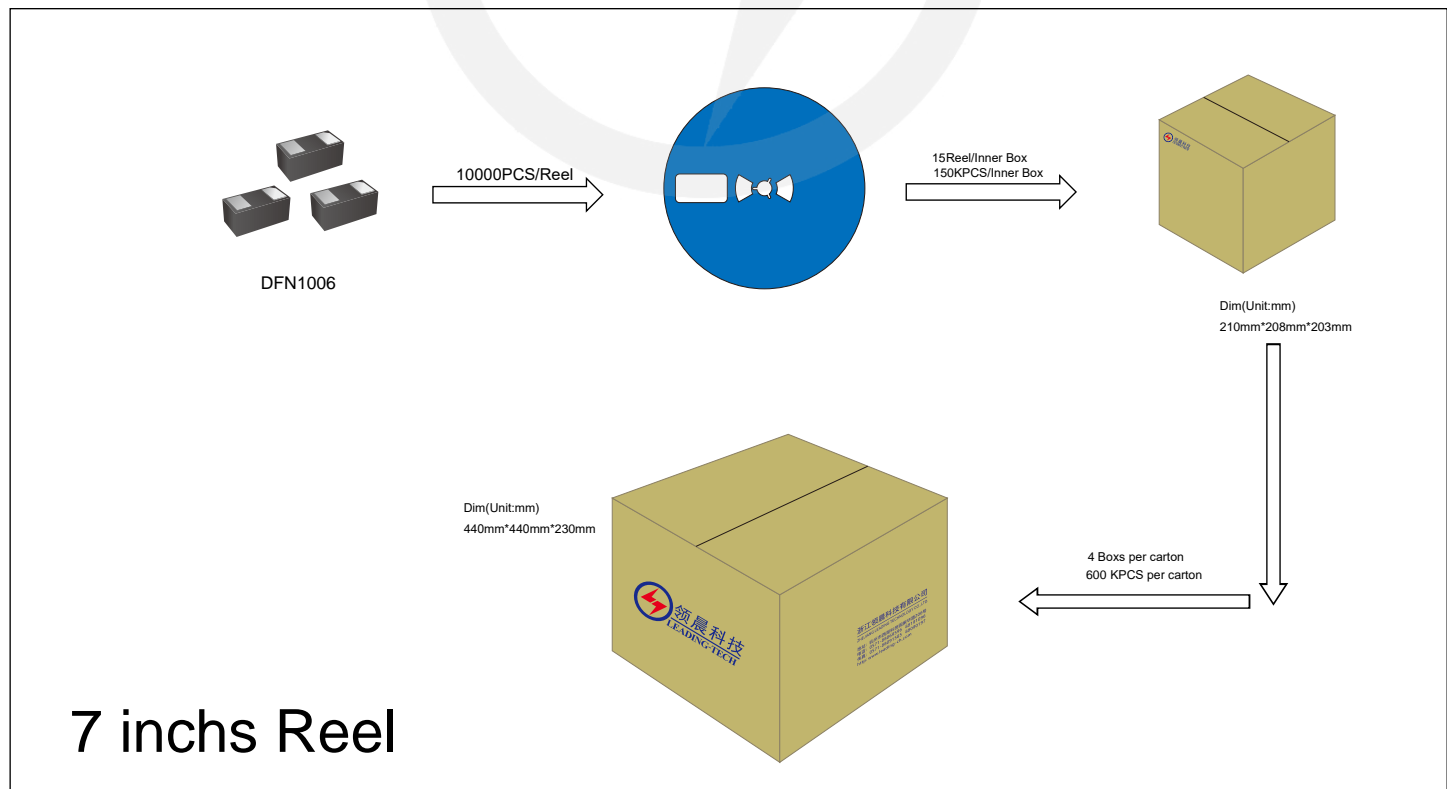


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2024.05.16	2024.05.16	3.0	New File	/	Ding	